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Kind regards,

Team Nexperia

# 74LVC8T245-Q100; 74LVCH8T245-Q100

8-bit dual supply translating transceiver; 3-state

Rev. 1 — 21 March 2013

Product data sheet

## 1. General description

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The 74LVC8T245-Q100; 74LVCH8T245-Q100 are 8-bit dual supply translating transceivers with 3-state outputs that enable bidirectional level translation. They feature two data input-output ports (pins An and Bn), a direction control input (DIR), an output enable input ( $\overline{OE}$ ) and dual supply pins ( $V_{CC(A)}$  and  $V_{CC(B)}$ ). Both  $V_{CC(A)}$  and  $V_{CC(B)}$  can be supplied at any voltage between 1.2 V and 5.5 V. This flexibility makes the device suitable for translating between any of the low voltage nodes (1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V and 5.0 V). Pins An,  $\overline{OE}$  and DIR are referenced to  $V_{CC(A)}$  and pins Bn are referenced to  $V_{CC(B)}$ . A HIGH on DIR allows transmission from An to Bn and a LOW on DIR allows transmission from Bn to An. The output enable input ( $\overline{OE}$ ) can be used to disable the outputs so the buses are effectively isolated.

The devices are fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing any damaging backflow current through the device when it is powered down. In suspend mode when either  $V_{CC(A)}$  or  $V_{CC(B)}$  are at GND level, both A port and B port are in the high-impedance OFF-state.

Active bus hold circuitry in the 74LVCH8T245-Q100 holds unused or floating data inputs at a valid logic level.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

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- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Wide supply voltage range:
  - ◆  $V_{CC(A)}$ : 1.2 V to 5.5 V
  - ◆  $V_{CC(B)}$ : 1.2 V to 5.5 V
- High noise immunity
- Complies with JEDEC standards:
  - ◆ JESD8-7 (1.2 V to 1.95 V)
  - ◆ JESD8-5 (1.8 V to 2.7 V)
  - ◆ JESD8C (2.7 V to 3.6 V)
  - ◆ JESD36 (4.5 V to 5.5 V)



- ESD protection:
  - ◆ MIL-STD-883, method 3015 Class 3A exceeds 4000 V
  - ◆ HBM JESD22-A114F Class 3A exceeds 4000 V
  - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0  $\Omega$ )
- Maximum data rates:
  - ◆ 420 Mbps (3.3 V to 5.0 V translation)
  - ◆ 210 Mbps (translate to 3.3 V)
  - ◆ 140 Mbps (translate to 2.5 V)
  - ◆ 75 Mbps (translate to 1.8 V)
  - ◆ 60 Mbps (translate to 1.5 V)
- Suspend mode
- Latch-up performance exceeds 100 mA per JESD 78B Class II
- $\pm 24$  mA output drive ( $V_{CC} = 3.0$  V)
- Inputs accept voltages up to 5.5 V
- Low power consumption: 30  $\mu$ A maximum  $I_{CC}$
- $I_{OFF}$  circuitry provides partial Power-down mode operation
- Multiple package options

### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC8T245PW-Q100 74LVCH8T245PW-Q100	-40 °C to +125 °C	TSSOP24	plastic thin shrink small outline package; 24 leads; body width 4.4 mm	SOT355-1
74LVC8T245BQ-Q100 74LVCH8T245BQ-Q100	-40 °C to +125 °C	DHVQFN24	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3.5 × 5.5 × 0.85 mm	SOT815-1

4. Functional diagram

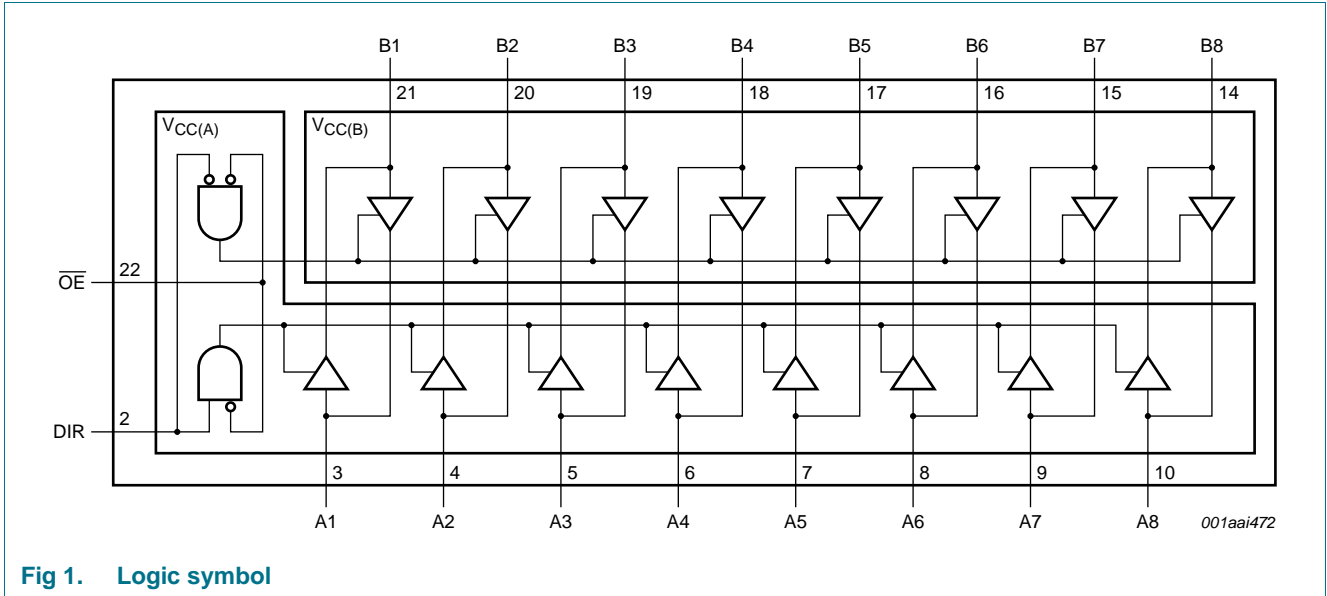


Fig 1. Logic symbol

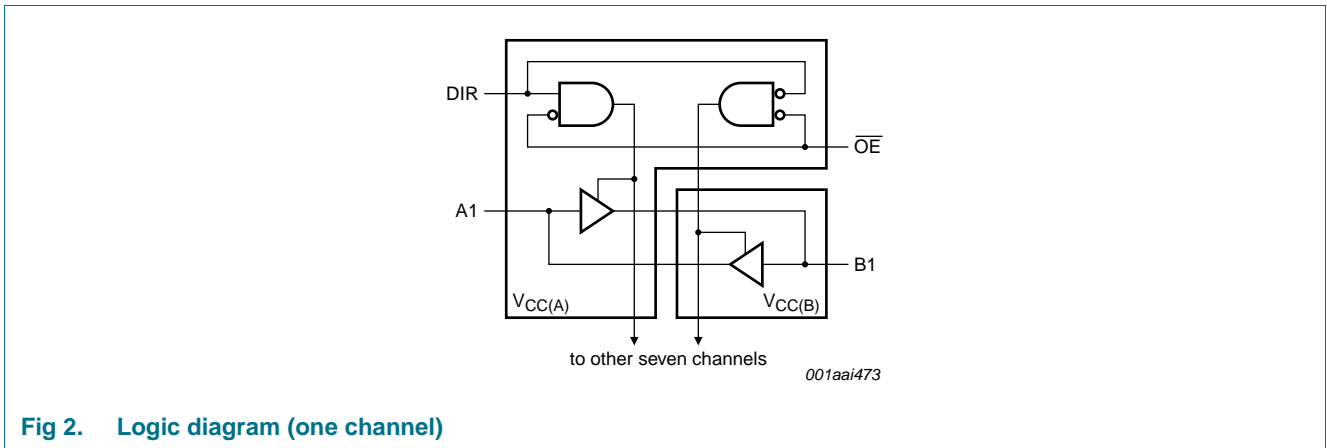
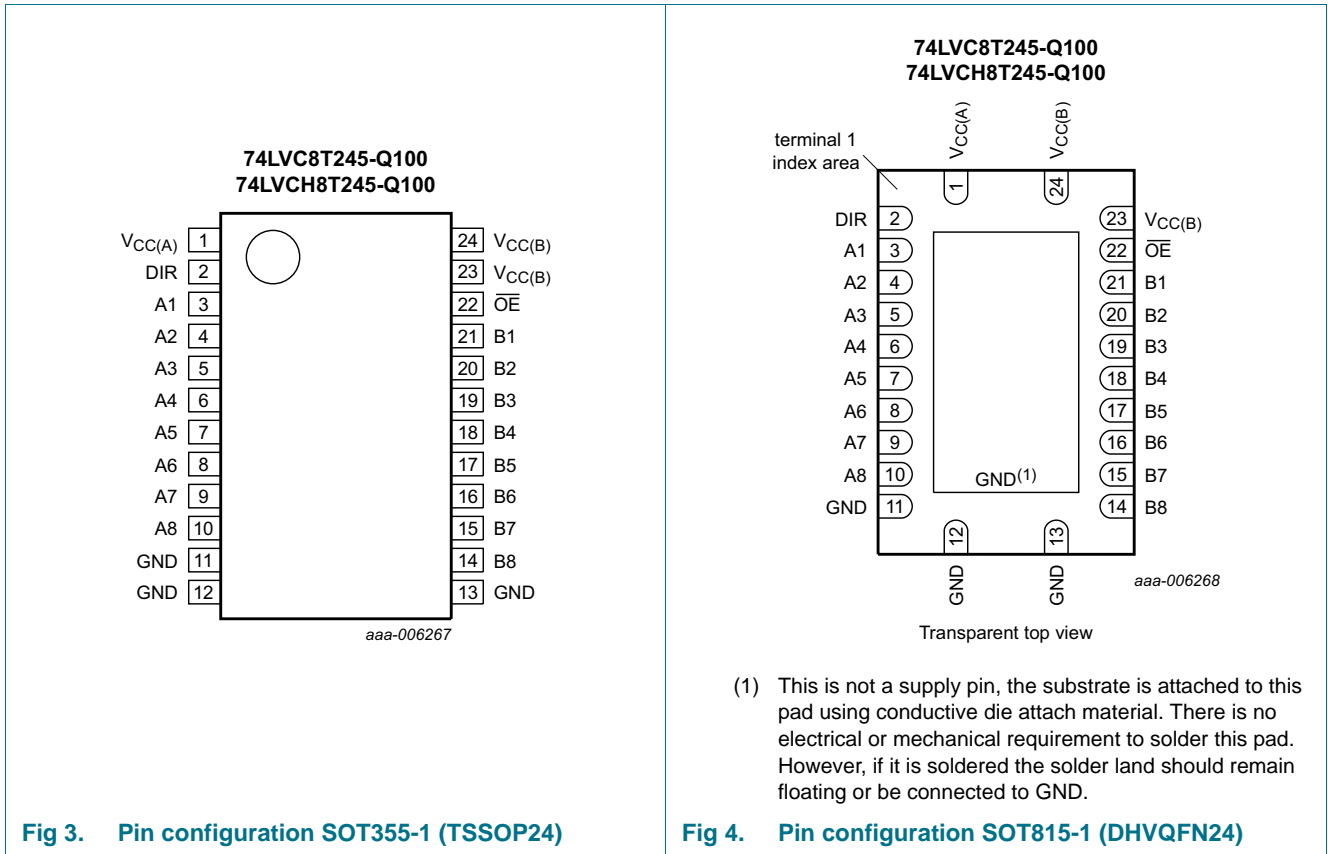


Fig 2. Logic diagram (one channel)

## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
V <sub>CC(A)</sub>	1	supply voltage A (An inputs/outputs, $\overline{OE}$ and DIR inputs are referenced to V <sub>CC(A)</sub> )
DIR	2	direction control
A1 to A8	3, 4, 5, 6, 7, 8, 9, 10	data input or output
GND <sup>[1]</sup>	11	ground (0 V)
GND <sup>[1]</sup>	12	ground (0 V)
GND <sup>[1]</sup>	13	ground (0 V)
B1 to B8	21, 20, 19, 18, 17, 16, 15, 14	data input or output
$\overline{OE}$	22	output enable input (active LOW)
V <sub>CC(B)</sub>	23	supply voltage B (Bn inputs/outputs are referenced to V <sub>CC(B)</sub> )
V <sub>CC(B)</sub>	24	supply voltage B (Bn inputs/outputs are referenced to V <sub>CC(B)</sub> )

[1] All GND pins must be connected to ground (0 V).

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Supply voltage	Input		Input/output <sup>[3]</sup>	
	$\overline{\text{OE}}$ <sup>[2]</sup>	DIR <sup>[2]</sup>	An <sup>[2]</sup>	Bn <sup>[2]</sup>
1.2 V to 5.5 V	L	L	An = Bn	input
1.2 V to 5.5 V	L	H	input	Bn = An
1.2 V to 5.5 V	H	X	Z	Z
GND <sup>[3]</sup>	X	X	Z	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

[2] The An inputs/outputs, DIR and  $\overline{\text{OE}}$  input circuit is referenced to  $V_{\text{CC(A)}}$ ; The Bn inputs/outputs circuit is referenced to  $V_{\text{CC(B)}}$ .

[3] If at least one of  $V_{\text{CC(A)}}$  or  $V_{\text{CC(B)}}$  is at GND level, the device goes into suspend mode.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{\text{CC(A)}}$	supply voltage A		-0.5	+6.5	V
$V_{\text{CC(B)}}$	supply voltage B		-0.5	+6.5	V
$I_{\text{IK}}$	input clamping current	$V_{\text{I}} < 0 \text{ V}$	-50	-	mA
$V_{\text{I}}$	input voltage		<sup>[1]</sup> -0.5	+6.5	V
$I_{\text{OK}}$	output clamping current	$V_{\text{O}} < 0 \text{ V}$	-50	-	mA
$V_{\text{O}}$	output voltage	Active mode	<sup>[1][2][3]</sup> -0.5	$V_{\text{CCO}} + 0.5$	V
		Suspend or 3-state mode	<sup>[1]</sup> -0.5	+6.5	V
$I_{\text{O}}$	output current	$V_{\text{O}} = 0 \text{ V}$ to $V_{\text{CCO}}$	<sup>[2]</sup> -	$\pm 50$	mA
$I_{\text{CC}}$	supply current	$I_{\text{CC(A)}}$ or $I_{\text{CC(B)}}$ ; per $V_{\text{CC}}$ pin	-	100	mA
$I_{\text{GND}}$	ground current	per GND pin	-100	-	mA
$T_{\text{stg}}$	storage temperature		-65	+150	°C
$P_{\text{tot}}$	total power dissipation	$T_{\text{amb}} = -40 \text{ °C}$ to $+125 \text{ °C}$	<sup>[4]</sup> -	500	mW

[1] The minimum input voltage ratings and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2]  $V_{\text{CCO}}$  is the supply voltage associated with the output port.

[3]  $V_{\text{CCO}} + 0.5 \text{ V}$  should not exceed 6.5 V.

[4] For TSSOP24 package:  $P_{\text{tot}}$  derates linearly at 5.5 mW/K above 60 °C.  
For DHVQFN24 package:  $P_{\text{tot}}$  derates linearly at 4.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_{CC(A)}$	supply voltage A		1.2	5.5	V	
$V_{CC(B)}$	supply voltage B		1.2	5.5	V	
$V_I$	input voltage		0	5.5	V	
$V_O$	output voltage	Active mode	[1]	$V_{CCO}$	V	
		Suspend or 3-state mode	0	5.5	V	
$T_{amb}$	ambient temperature		-40	+125	°C	
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CCI} = 1.2\text{ V}$	[2]	-	20	ns/V
		$V_{CCI} = 1.4\text{ V to }1.95\text{ V}$	-	-	20	ns/V
		$V_{CCI} = 2.3\text{ V to }2.7\text{ V}$	-	-	20	ns/V
		$V_{CCI} = 3\text{ V to }3.6\text{ V}$	-	-	10	ns/V
		$V_{CCI} = 4.5\text{ V to }5.5\text{ V}$	-	-	5	ns/V

[1]  $V_{CCO}$  is the supply voltage associated with the output port.

[2]  $V_{CCI}$  is the supply voltage associated with the input port.

## 9. Static characteristics

**Table 6. Typical static characteristics at  $T_{amb} = 25\text{ °C}$**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	[1]	-	-	-
		$I_O = -3\text{ mA}$ ; $V_{CCO} = 1.2\text{ V}$	-	1.09	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	[1]	-	-	-
		$I_O = 3\text{ mA}$ ; $V_{CCO} = 1.2\text{ V}$	-	0.07	-	V
$I_I$	input leakage current	DIR, $\overline{OE}$ input; $V_I = 0\text{ V to }5.5\text{ V}$ ; $V_{CCI} = 1.2\text{ V to }5.5\text{ V}$	[2]	-	-	$\pm 1\text{ }\mu\text{A}$
$I_{BHL}$	bus hold LOW current	A or B port; $V_I = 0.42\text{ V}$ ; $V_{CCI} = 1.2\text{ V}$	[2]	-	19	$\mu\text{A}$
$I_{BHH}$	bus hold HIGH current	A or B port; $V_I = 0.78\text{ V}$ ; $V_{CCI} = 1.2\text{ V}$	[2]	-	-19	$\mu\text{A}$
$I_{BHLO}$	bus hold LOW overdrive current	A or B port; $V_{CCI} = 1.2\text{ V}$	[2][3]	-	19	$\mu\text{A}$
$I_{BHHO}$	bus hold HIGH overdrive current	A or B port; $V_{CCI} = 1.2\text{ V}$	[2][3]	-	-19	$\mu\text{A}$
$I_{OZ}$	OFF-state output current	A or B port; $V_O = 0\text{ V or }V_{CCO}$ ; $V_{CCO} = 1.2\text{ V to }5.5\text{ V}$	[1]	-	-	$\pm 1\text{ }\mu\text{A}$
		suspend mode A port; $V_O = 0\text{ V or }V_{CCO}$ ; $V_{CC(A)} = 5.5\text{ V}$ ; $V_{CC(B)} = 0\text{ V}$	[1]	-	-	$\pm 1\text{ }\mu\text{A}$
		suspend mode B port; $V_O = 0\text{ V or }V_{CCO}$ ; $V_{CC(A)} = 0\text{ V}$ ; $V_{CC(B)} = 5.5\text{ V}$	[1]	-	-	$\pm 1\text{ }\mu\text{A}$

**Table 6. Typical static characteristics at  $T_{amb} = 25\text{ °C}$  ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{OFF}$	power-off leakage current	A port; $V_I$ or $V_O = 0\text{ V to }5.5\text{ V}$ ; $V_{CC(A)} = 0\text{ V}$ ; $V_{CC(B)} = 1.2\text{ V to }5.5\text{ V}$	-	-	$\pm 1$	$\mu\text{A}$
		B port; $V_I$ or $V_O = 0\text{ V to }5.5\text{ V}$ ; $V_{CC(B)} = 0\text{ V}$ ; $V_{CC(A)} = 1.2\text{ V to }5.5\text{ V}$	-	-	$\pm 1$	$\mu\text{A}$
$C_I$	input capacitance	DIR, $\overline{OE}$ input; $V_I = 0\text{ V or }3.3\text{ V}$ ; $V_{CC(A)} = 3.3\text{ V}$	-	3	-	pF
$C_{I/O}$	input/output capacitance	A and B port; $V_O = 3.3\text{ V or }0\text{ V}$ ; $V_{CC(A)} = V_{CC(B)} = 3.3\text{ V}$	-	6.5	-	pF

[1]  $V_{CCO}$  is the supply voltage associated with the output port.

[2]  $V_{CCI}$  is the supply voltage associated with the data input port.

[3] To guarantee the node switches, an external driver must source/sink at least  $I_{BHLO} / I_{BHHO}$  when the input is in the range  $V_{IL}$  to  $V_{IH}$ .

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	data input [1]					
		$V_{CCI} = 1.2\text{ V}$	$0.8V_{CCI}$	-	$0.8V_{CCI}$	-	V
		$V_{CCI} = 1.4\text{ V to }1.95\text{ V}$	$0.65V_{CCI}$	-	$0.65V_{CCI}$	-	V
		$V_{CCI} = 2.3\text{ V to }2.7\text{ V}$	1.7	-	1.7	-	V
		$V_{CCI} = 3.0\text{ V to }3.6\text{ V}$	2.0	-	2.0	-	V
		$V_{CCI} = 4.5\text{ V to }5.5\text{ V}$	$0.7V_{CCI}$	-	$0.7V_{CCI}$	-	V
		DIR, $\overline{OE}$ input					
		$V_{CCI} = 1.2\text{ V}$	$0.8V_{CC(A)}$	-	$0.8V_{CC(A)}$	-	V
		$V_{CCI} = 1.4\text{ V to }1.95\text{ V}$	$0.65V_{CC(A)}$	-	$0.65V_{CC(A)}$	-	V
		$V_{CCI} = 2.3\text{ V to }2.7\text{ V}$	1.7	-	1.7	-	V
		$V_{CCI} = 3.0\text{ V to }3.6\text{ V}$	2.0	-	2.0	-	V
$V_{CCI} = 4.5\text{ V to }5.5\text{ V}$	$0.7V_{CC(A)}$	-	$0.7V_{CC(A)}$	-	V		
$V_{IL}$	LOW-level input voltage	data input [1]					
		$V_{CCI} = 1.2\text{ V}$	-	$0.2V_{CCI}$	-	$0.2V_{CCI}$	V
		$V_{CCI} = 1.4\text{ V to }1.95\text{ V}$	-	$0.35V_{CCI}$	-	$0.35V_{CCI}$	V
		$V_{CCI} = 2.3\text{ V to }2.7\text{ V}$	-	0.7	-	0.7	V
		$V_{CCI} = 3.0\text{ V to }3.6\text{ V}$	-	0.8	-	0.8	V
		$V_{CCI} = 4.5\text{ V to }5.5\text{ V}$	-	$0.3V_{CCI}$	-	$0.3V_{CCI}$	V
		DIR, $\overline{OE}$ input					
		$V_{CCI} = 1.2\text{ V}$	-	$0.2V_{CC(A)}$	-	$0.2V_{CC(A)}$	V
		$V_{CCI} = 1.4\text{ V to }1.95\text{ V}$	-	$0.35V_{CC(A)}$	-	$0.35V_{CC(A)}$	V
		$V_{CCI} = 2.3\text{ V to }2.7\text{ V}$	-	0.7	-	0.7	V
		$V_{CCI} = 3.0\text{ V to }3.6\text{ V}$	-	0.8	-	0.8	V
$V_{CCI} = 4.5\text{ V to }5.5\text{ V}$	-	$0.3V_{CC(A)}$	-	$0.3V_{CC(A)}$	V		



**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Max	Min	Max	
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub>					
		I <sub>O</sub> = -100 μA; V <sub>CCO</sub> = 1.2 V to 4.5 V [2]	V <sub>CCO</sub> - 0.1	-	V <sub>CCO</sub> - 0.1	-	V
		I <sub>O</sub> = -6 mA; V <sub>CCO</sub> = 1.4 V	1.0	-	1.0	-	V
		I <sub>O</sub> = -8 mA; V <sub>CCO</sub> = 1.65 V	1.2	-	1.2	-	V
		I <sub>O</sub> = -12 mA; V <sub>CCO</sub> = 2.3 V	1.9	-	1.9	-	V
		I <sub>O</sub> = -24 mA; V <sub>CCO</sub> = 3.0 V	2.4	-	2.4	-	V
		I <sub>O</sub> = -32 mA; V <sub>CCO</sub> = 4.5 V	3.8	-	3.8	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IL</sub> [2]					
		I <sub>O</sub> = 100 μA; V <sub>CCO</sub> = 1.2 V to 4.5 V	-	0.1	-	0.1	V
		I <sub>O</sub> = 6 mA; V <sub>CCO</sub> = 1.4 V	-	0.3	-	0.3	V
		I <sub>O</sub> = 8 mA; V <sub>CCO</sub> = 1.65 V	-	0.45	-	0.45	V
		I <sub>O</sub> = 12 mA; V <sub>CCO</sub> = 2.3 V	-	0.3	-	0.3	V
		I <sub>O</sub> = 24 mA; V <sub>CCO</sub> = 3.0 V	-	0.55	-	0.55	V
		I <sub>O</sub> = 32 mA; V <sub>CCO</sub> = 4.5 V	-	0.55	-	0.55	V
I <sub>I</sub>	input leakage current	DIR, $\overline{\text{OE}}$ input; V <sub>I</sub> = 0 V to 5.5 V; V <sub>CCI</sub> = 1.2 V to 5.5 V	-	±2	-	±10	μA
I <sub>BHL</sub>	bus hold LOW current	A or B port [1]					
		V <sub>I</sub> = 0.49 V; V <sub>CCI</sub> = 1.4 V	15	-	10	-	μA
		V <sub>I</sub> = 0.58 V; V <sub>CCI</sub> = 1.65 V	25	-	20	-	μA
		V <sub>I</sub> = 0.70 V; V <sub>CCI</sub> = 2.3 V	45	-	45	-	μA
		V <sub>I</sub> = 0.80 V; V <sub>CCI</sub> = 3.0 V	100	-	80	-	μA
		V <sub>I</sub> = 1.35 V; V <sub>CCI</sub> = 4.5 V	100	-	100	-	μA
I <sub>BHH</sub>	bus hold HIGH current	A or B port [1]					
		V <sub>I</sub> = 0.91 V; V <sub>CCI</sub> = 1.4 V	-15	-	-10	-	μA
		V <sub>I</sub> = 1.07 V; V <sub>CCI</sub> = 1.65 V	-25	-	-20	-	μA
		V <sub>I</sub> = 1.70 V; V <sub>CCI</sub> = 2.3 V	-45	-	-45	-	μA
		V <sub>I</sub> = 2.00 V; V <sub>CCI</sub> = 3.0 V	-100	-	-80	-	μA
		V <sub>I</sub> = 3.15 V; V <sub>CCI</sub> = 4.5 V	-100	-	-100	-	μA
I <sub>BHLO</sub>	bus hold LOW overdrive current	A or B port [1][3]					
		V <sub>CCI</sub> = 1.6 V	125	-	125	-	μA
		V <sub>CCI</sub> = 1.95 V	200	-	200	-	μA
		V <sub>CCI</sub> = 2.7 V	300	-	300	-	μA
		V <sub>CCI</sub> = 3.6 V	500	-	500	-	μA
		V <sub>CCI</sub> = 5.5 V	900	-	900	-	μA

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Max	Min	Max	
I <sub>BHHO</sub>	bus hold HIGH overdrive current	A or B port <a href="#">[1][3]</a>					
		V <sub>CCI</sub> = 1.6 V	-125	-	-125	-	μA
		V <sub>CCI</sub> = 1.95 V	-200	-	-200	-	μA
		V <sub>CCI</sub> = 2.7 V	-300	-	-300	-	μA
		V <sub>CCI</sub> = 3.6 V	-500	-	-500	-	μA
		V <sub>CCI</sub> = 5.5 V	-900	-	-900	-	μA
I <sub>OZ</sub>	OFF-state output current	A or B port; V <sub>O</sub> = 0 V or V <sub>CCO</sub> ; V <sub>CCO</sub> = 1.2 V to 5.5 V <a href="#">[2]</a>	-	±2	-	±10	μA
		suspend mode A port; V <sub>O</sub> = 0 V or V <sub>CCO</sub> ; V <sub>CC(A)</sub> = 5.5 V; V <sub>CC(B)</sub> = 0 V <a href="#">[2]</a>	-	±2	-	±10	μA
		suspend mode B port; V <sub>O</sub> = 0 V or V <sub>CCO</sub> ; V <sub>CC(A)</sub> = 0 V; V <sub>CC(B)</sub> = 5.5 V <a href="#">[2]</a>	-	±2	-	±10	μA
I <sub>OFF</sub>	power-off leakage current	A port; V <sub>I</sub> or V <sub>O</sub> = 0 V to 5.5 V; V <sub>CC(A)</sub> = 0 V; V <sub>CC(B)</sub> = 1.2 V to 5.5 V	-	±2	-	±10	μA
		B port; V <sub>I</sub> or V <sub>O</sub> = 0 V to 5.5 V; V <sub>CC(B)</sub> = 0 V; V <sub>CC(A)</sub> = 1.2 V to 5.5 V	-	±2	-	±10	μA
I <sub>CC</sub>	supply current	A port; V <sub>I</sub> = 0 V or V <sub>CCI</sub> ; I <sub>O</sub> = 0 A <a href="#">[1]</a>					
		V <sub>CC(A)</sub> , V <sub>CC(B)</sub> = 1.2 V to 5.5 V	-	15	-	20	μA
		V <sub>CC(A)</sub> = 5.5 V; V <sub>CC(B)</sub> = 0 V	-	15	-	20	μA
		V <sub>CC(A)</sub> = 0 V; V <sub>CC(B)</sub> = 5.5 V	-2	-	-4	-	μA
		B port; V <sub>I</sub> = 0 V or V <sub>CCI</sub> ; I <sub>O</sub> = 0 A					
		V <sub>CC(A)</sub> , V <sub>CC(B)</sub> = 1.2 V to 5.5 V	-	15	-	20	μA
		V <sub>CC(B)</sub> = 0 V; V <sub>CC(A)</sub> = 5.5 V	-2	-	-4	-	μA
		V <sub>CC(B)</sub> = 5.5 V; V <sub>CC(A)</sub> = 0 V	-	15	-	20	μA
A plus B port (I <sub>CC(A)</sub> + I <sub>CC(B)</sub> ); I <sub>O</sub> = 0 A; V <sub>I</sub> = 0 V or V <sub>CCI</sub>							
		V <sub>CC(A)</sub> , V <sub>CC(B)</sub> = 1.2 V to 5.5 V	-	25	-	30	μA
ΔI <sub>CC</sub>	additional supply current	per input; V <sub>CC(A)</sub> , V <sub>CC(B)</sub> = 3.0 V to 5.5 V					
		DIR and $\overline{OE}$ input; DIR or $\overline{OE}$ input at V <sub>CC(A)</sub> - 0.6 V; A port at V <sub>CC(A)</sub> or GND; B port = open	-	50	-	75	μA
		A port; A port at V <sub>CC(A)</sub> - 0.6 V; DIR at V <sub>CC(A)</sub> ; B port = open <a href="#">[4]</a>	-	50	-	75	μA
		B port; B port at V <sub>CC(B)</sub> - 0.6 V; DIR at GND; A port = open <a href="#">[4]</a>	-	50	-	75	μA

[1] V<sub>CCI</sub> is the supply voltage associated with the data input port.

[2] V<sub>CCO</sub> is the supply voltage associated with the output port.

[3] To guarantee the node switches, an external driver must source/sink at least I<sub>BHLO</sub> / I<sub>BHHO</sub> when the input is in the range V<sub>IL</sub> to V<sub>IH</sub>.

[4] For non-bus hold parts only (74LVC8T245-Q100).

## 10. Dynamic characteristics

**Table 8. Typical dynamic characteristics at  $V_{CC(A)} = 1.2\text{ V}$  and  $T_{amb} = 25\text{ °C}$ [1]**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#); for waveforms see [Figure 5](#) and [Figure 6](#).

Symbol	Parameter	Conditions	$V_{CC(B)}$						Unit
			1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V	
$t_{pd}$	propagation delay	An to Bn	11.0	8.5	7.4	6.2	5.7	5.4	ns
		Bn to An	11.0	10.0	9.5	9.1	8.9	8.9	ns
$t_{dis}$	disable time	$\overline{OE}$ to An	9.5	9.5	9.5	9.5	9.5	9.5	ns
		$\overline{OE}$ to Bn	10.2	8.2	7.8	6.7	7.3	6.4	ns
$t_{en}$	enable time	$\overline{OE}$ to An	13.5	13.5	13.5	13.5	13.5	13.5	ns
		$\overline{OE}$ to Bn	13.6	10.3	8.9	7.5	7.1	7.0	ns

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ ;  $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ ;  $t_{en}$  is the same as  $t_{PZL}$  and  $t_{PZH}$ .

**Table 9. Typical dynamic characteristics at  $V_{CC(B)} = 1.2\text{ V}$  and  $T_{amb} = 25\text{ °C}$ [1]**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#); for waveforms see [Figure 5](#) and [Figure 6](#).

Symbol	Parameter	Conditions	$V_{CC(A)}$						Unit
			1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	5.0 V	
$t_{pd}$	propagation delay	An to Bn	11.0	10.0	9.5	9.1	8.9	8.8	ns
		Bn to An	11.0	8.5	7.3	6.2	5.7	5.4	ns
$t_{dis}$	disable time	$\overline{OE}$ to An	9.5	6.8	5.4	3.8	4.1	3.1	ns
		$\overline{OE}$ to Bn	10.2	9.1	8.6	8.1	7.8	7.8	ns
$t_{en}$	enable time	$\overline{OE}$ to An	13.5	9.0	6.9	4.8	3.8	3.2	ns
		$\overline{OE}$ to Bn	13.6	12.5	12.0	11.5	11.4	11.4	ns

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ ;  $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ ;  $t_{en}$  is the same as  $t_{PZL}$  and  $t_{PZH}$ .

**Table 10. Typical power dissipation capacitance at  $V_{CC(A)} = V_{CC(B)}$  and  $T_{amb} = 25\text{ °C}$ [1][2]**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	$V_{CC(A)}$ and $V_{CC(B)}$				Unit
			1.8 V	2.5 V	3.3 V	5.0 V	
$C_{PD}$	power dissipation capacitance	A port: (direction A to B); B port: (direction B to A)	1	1	1	2	pF
		A port: (direction B to A); B port: (direction A to B)	13	13	13	13	pF

[1]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = load capacitance in pF;

$V_{CC}$  = supply voltage in V;

$N$  = number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

[2]  $f_i = 10\text{ MHz}$ ;  $V_i = \text{GND to } V_{CC}$ ;  $t_r = t_f = 1\text{ ns}$ ;  $C_L = 0\text{ pF}$ ;  $R_L = \infty\ \Omega$ .

**Table 11. Dynamic characteristics for temperature range –40 °C to +85 °C<sup>[1]</sup>**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#); for wave forms see [Figure 5](#) and [Figure 6](#).

Symbol	Parameter	Conditions	V <sub>CC(B)</sub>										Unit
			1.5 V ± 0.1 V		1.8 V ± 0.15 V		2.5 V ± 0.2 V		3.3 V ± 0.3 V		5.0 V ± 0.5 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
<b>V<sub>CC(A)</sub> = 1.5 V ± 0.1 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.7	27	1.7	23	1.3	18	1.0	15	0.8	13	ns
		Bn to An	0.9	27	0.9	25	0.8	23	0.7	23	0.7	22	ns
t <sub>dis</sub>	disable time	$\overline{OE}$ to An	1.5	30	1.5	30	1.5	30	1.5	30	1.4	30	ns
		$\overline{OE}$ to Bn	2.4	34	2.4	33	1.9	15	1.7	14	1.3	12	ns
t <sub>en</sub>	enable time	$\overline{OE}$ to An	0.4	34	0.4	34	0.4	34	0.4	34	0.4	34	ns
		$\overline{OE}$ to Bn	1.8	36	1.8	34	1.5	18	1.2	15	0.9	13	ns
<b>V<sub>CC(A)</sub> = 1.8 V ± 0.15 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.7	25	1.7	21.9	1.3	9.2	1.0	7.4	0.8	7.1	ns
		Bn to An	0.9	23	0.9	23.8	0.8	23.6	0.7	23.4	0.7	23.4	ns
t <sub>dis</sub>	disable time	$\overline{OE}$ to An	1.5	30	1.5	29.6	1.5	29.4	1.5	29.3	1.4	29.2	ns
		$\overline{OE}$ to Bn	2.4	33	2.4	32.2	1.9	13.1	1.7	12.0	1.3	10.3	ns
t <sub>en</sub>	enable time	$\overline{OE}$ to An	0.4	24	0.4	24.0	0.4	23.8	0.4	23.7	0.4	23.7	ns
		$\overline{OE}$ to Bn	1.8	34	1.8	32.0	1.5	16.0	1.2	12.6	0.9	10.8	ns
<b>V<sub>CC(A)</sub> = 2.5 V ± 0.2 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.5	23	1.5	21.4	1.2	9.0	0.8	6.2	0.6	4.8	ns
		Bn to An	1.2	18	1.2	9.3	1.0	9.1	1.0	8.9	0.9	8.8	ns
t <sub>dis</sub>	disable time	$\overline{OE}$ to An	1.4	9.0	1.4	9.0	1.4	9.0	1.4	9.0	1.4	9.0	ns
		$\overline{OE}$ to Bn	2.3	31	2.3	29.6	1.8	11.0	1.7	9.3	0.9	6.9	ns
t <sub>en</sub>	enable time	$\overline{OE}$ to An	1.0	10.9	1.0	10.9	1.0	10.9	1.0	10.9	1.0	10.9	ns
		$\overline{OE}$ to Bn	1.7	32	1.7	28.2	1.5	12.9	1.2	9.4	1.0	6.9	ns
<b>V<sub>CC(A)</sub> = 3.3 V ± 0.3 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.5	23	1.5	21.2	1.1	8.8	0.8	6.3	0.5	4.4	ns
		Bn to An	0.8	15	0.8	7.2	0.8	6.2	0.7	6.1	0.6	6.0	ns
t <sub>dis</sub>	disable time	$\overline{OE}$ to An	1.6	8.2	1.6	8.2	1.6	8.2	1.6	8.2	1.6	8.2	ns
		$\overline{OE}$ to Bn	2.1	30	2.1	29.0	1.7	10.3	1.5	8.6	0.8	6.3	ns
t <sub>en</sub>	enable time	$\overline{OE}$ to An	0.8	8.1	0.8	8.1	0.8	8.1	0.8	8.1	0.8	8.1	ns
		$\overline{OE}$ to Bn	1.8	31	1.8	27.7	1.4	12.4	1.1	8.5	0.9	6.4	ns
<b>V<sub>CC(A)</sub> = 5.0 V ± 0.5 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.5	22	1.5	21.4	1.0	8.8	0.7	6.0	0.4	4.2	ns
		Bn to An	0.7	13	0.7	7.0	0.4	4.8	0.3	4.5	0.3	4.3	ns
t <sub>dis</sub>	disable time	$\overline{OE}$ to An	0.3	5.4	0.3	5.4	0.3	5.4	0.3	5.4	0.3	5.4	ns
		$\overline{OE}$ to Bn	2.0	30	2.0	28.7	1.6	9.7	1.4	8.0	0.7	5.7	ns
t <sub>en</sub>	enable time	$\overline{OE}$ to An	0.7	6.4	0.7	6.4	0.7	6.4	0.7	6.4	0.7	6.4	ns
		$\overline{OE}$ to Bn	1.5	31	1.5	27.6	1.3	11.4	1.0	8.1	0.9	6.0	ns

[1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>; t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>; t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.

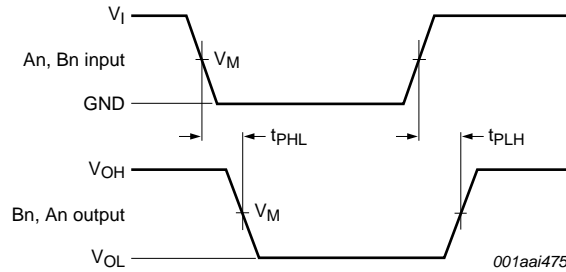
**Table 12. Dynamic characteristics for temperature range –40 °C to +125 °C<sup>[1]</sup>**

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#); for wave forms see [Figure 5](#) and [Figure 6](#).

Symbol	Parameter	Conditions	V <sub>CC(B)</sub>										Unit
			1.5 V ± 0.1 V		1.8 V ± 0.15 V		2.5 V ± 0.2 V		3.3 V ± 0.3 V		5.0 V ± 0.5 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
<b>V<sub>CC(A)</sub> = 1.5 V ± 0.1 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.7	32	1.7	27	1.3	21	1.0	18	0.8	16	ns
		Bn to An	0.9	32	0.9	30	0.8	28	0.7	28	0.7	26	ns
t <sub>dis</sub>	disable time	$\overline{\text{OE}}$ to An	1.5	34	1.5	34	1.5	34	1.5	34	1.4	34	ns
		$\overline{\text{OE}}$ to Bn	2.4	41	2.4	40	1.9	18	1.7	17	1.3	15	ns
t <sub>en</sub>	enable time	$\overline{\text{OE}}$ to An	0.4	40	0.4	40	0.4	40	0.4	40	0.4	40	ns
		$\overline{\text{OE}}$ to Bn	1.8	43	1.8	41	1.5	22	1.2	18	0.9	16	ns
<b>V<sub>CC(A)</sub> = 1.8 V ± 0.15 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.7	30	1.7	25.9	1.3	13.2	1.0	11.4	0.8	11.1	ns
		Bn to An	0.9	27	0.9	28.8	0.8	27.6	0.7	27.4	0.7	27.4	ns
t <sub>dis</sub>	disable time	$\overline{\text{OE}}$ to An	1.5	34	1.5	33.6	1.5	33.4	1.5	33.3	1.4	33.2	ns
		$\overline{\text{OE}}$ to Bn	2.4	40	2.4	36.2	1.9	17.1	1.7	16.0	1.3	14.3	ns
t <sub>en</sub>	enable time	$\overline{\text{OE}}$ to An	0.4	28	0.4	28	0.4	27.8	0.4	27.7	0.4	27.7	ns
		$\overline{\text{OE}}$ to Bn	1.8	41	1.8	40	1.5	20	1.2	16.6	0.9	14.8	ns
<b>V<sub>CC(A)</sub> = 2.5 V ± 0.2 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.5	28	1.5	25.4	1.2	13	0.8	10.2	0.6	8.8	ns
		Bn to An	1.2	23	1.2	13.3	1.0	13.1	1.0	12.9	0.9	12.8	ns
t <sub>dis</sub>	disable time	$\overline{\text{OE}}$ to An	1.4	13	1.4	13	1.4	13	1.4	13	1.4	13	ns
		$\overline{\text{OE}}$ to Bn	2.3	37	2.3	33.6	1.8	15	1.7	14.3	0.9	10.9	ns
t <sub>en</sub>	enable time	$\overline{\text{OE}}$ to An	1.0	17.2	1.0	17.2	1.0	17.3	1.0	17.2	1.0	17.3	ns
		$\overline{\text{OE}}$ to Bn	1.7	38	1.7	32.2	1.5	18.1	1.2	14.1	1.0	11.2	ns
<b>V<sub>CC(A)</sub> = 3.3 V ± 0.3 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.5	28	1.5	25.2	1.1	12.8	0.8	10.3	0.5	10.4	ns
		Bn to An	0.8	18	0.8	11.2	0.8	10.2	0.7	10.1	0.6	10	ns
t <sub>dis</sub>	disable time	$\overline{\text{OE}}$ to An	1.6	12.2	1.6	12.2	1.6	12.2	1.6	12.2	1.6	12.2	ns
		$\overline{\text{OE}}$ to Bn	2.1	36	2.1	33	1.7	14.3	1.5	12.6	0.8	10.3	ns
t <sub>en</sub>	enable time	$\overline{\text{OE}}$ to An	0.8	14.1	0.8	14.1	0.8	13.6	0.8	13.2	0.8	13.6	ns
		$\overline{\text{OE}}$ to Bn	1.8	37	1.8	31.7	1.4	18.4	1.1	12.9	0.9	10.9	ns
<b>V<sub>CC(A)</sub> = 5.0 V ± 0.5 V</b>													
t <sub>pd</sub>	propagation delay	An to Bn	1.5	26	1.5	25.4	1.0	12.8	0.7	10	0.4	8.2	ns
		Bn to An	0.7	16	0.7	11	0.4	8.8	0.3	8.5	0.3	8.3	ns
t <sub>dis</sub>	disable time	$\overline{\text{OE}}$ to An	0.3	9.4	0.3	9.4	0.3	9.4	0.3	9.4	0.3	9.4	ns
		$\overline{\text{OE}}$ to Bn	2.0	36	2.0	32.7	1.6	13.7	1.4	12	0.7	9.7	ns
t <sub>en</sub>	enable time	$\overline{\text{OE}}$ to An	0.7	10.9	0.7	10.9	0.7	10.9	0.7	10.9	0.7	10.9	ns
		$\overline{\text{OE}}$ to Bn	1.5	37	1.5	31.6	1.3	18.4	1.0	13.7	0.9	10.7	ns

[1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>; t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>; t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.

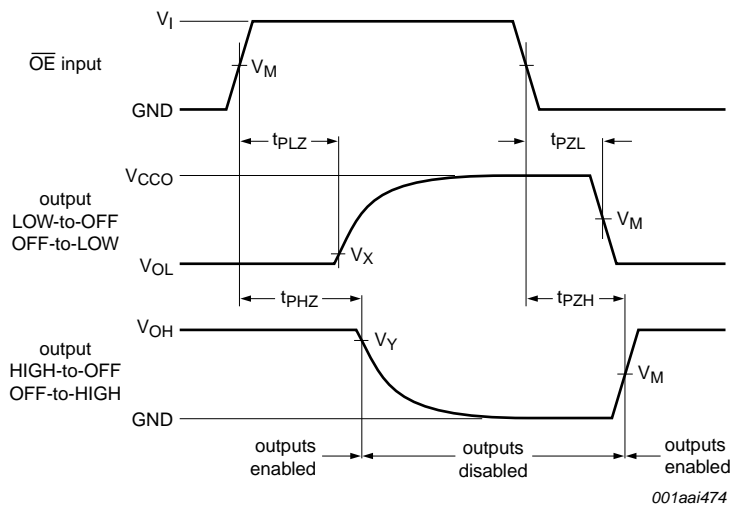
11. Waveforms



Measurement points are given in [Table 13](#).

$V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 5. The data input (An, Bn) to output (Bn, An) propagation delay times**



Measurement points are given in [Table 13](#).

$V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

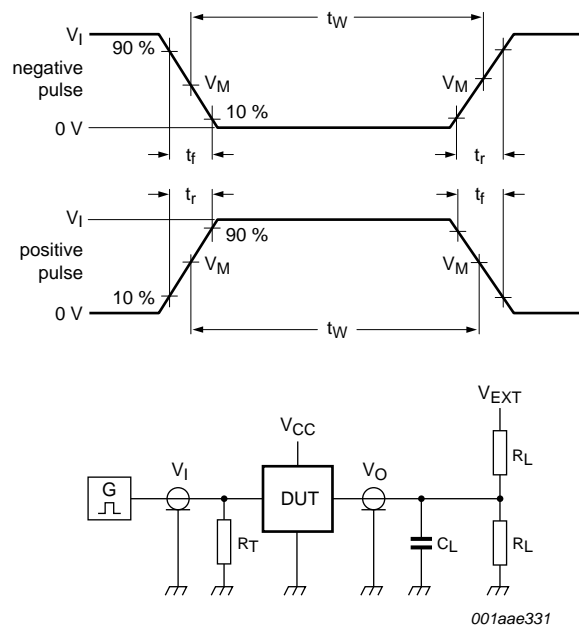
**Fig 6. Enable and disable times**

**Table 13. Measurement points**

Supply voltage	Input <sup>[1]</sup>	Output <sup>[2]</sup>		
$V_{CC(A)}, V_{CC(B)}$	$V_M$	$V_M$	$V_X$	$V_Y$
1.2 V to 1.6 V	$0.5V_{CCI}$	$0.5V_{CCO}$	$V_{OL} + 0.1 V$	$V_{OH} - 0.1 V$
1.65 V to 2.7 V	$0.5V_{CCI}$	$0.5V_{CCO}$	$V_{OL} + 0.15 V$	$V_{OH} - 0.15 V$
3.0 V to 5.5 V	$0.5V_{CCI}$	$0.5V_{CCO}$	$V_{OL} + 0.3 V$	$V_{OH} - 0.3 V$

[1]  $V_{CCI}$  is the supply voltage associated with the data input port.

[2]  $V_{CCO}$  is the supply voltage associated with the output port.



Test data is given in [Table 14](#).

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 7. Load circuitry for switching times**

**Table 14. Test data**

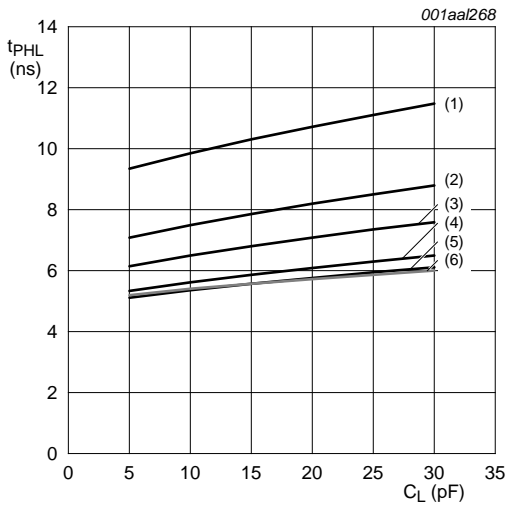
Supply voltage	Input		Load		$V_{EXT}$		
$V_{CC(A)}, V_{CC(B)}$	$V_I$ <sup>[1]</sup>	$\Delta t/\Delta V$ <sup>[2]</sup>	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$ <sup>[3]</sup>
1.2 V to 5.5 V	$V_{CCI}$	$\leq 1.0 \text{ ns/V}$	15 pF	2 k $\Omega$	open	GND	$2V_{CCO}$

[1]  $V_{CCI}$  is the supply voltage associated with the data input port.

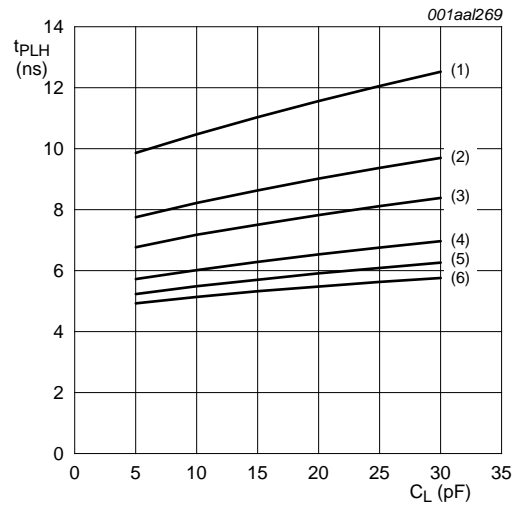
[2]  $dV/dt \geq 1.0 \text{ V/ns}$ .

[3]  $V_{CCO}$  is the supply voltage associated with the output port.

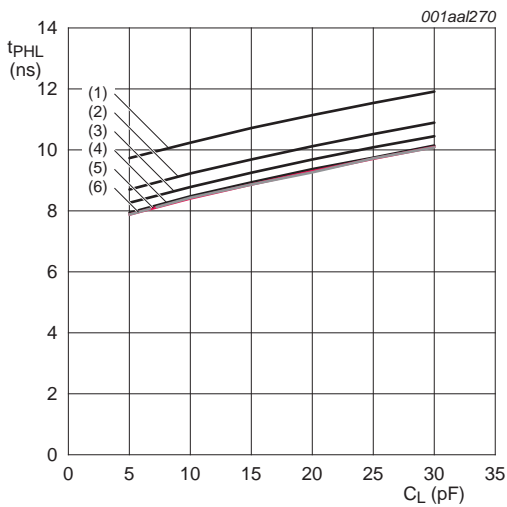
12. Typical propagation delay characteristics



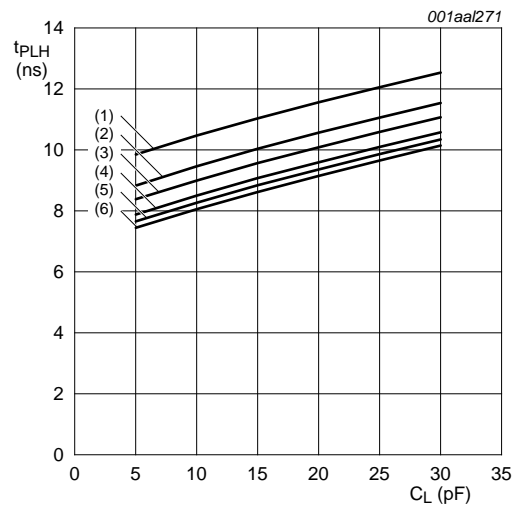
a. HIGH to LOW propagation delay (A to B)



b. LOW to HIGH propagation delay (A to B)



c. HIGH to LOW propagation delay (B to A)

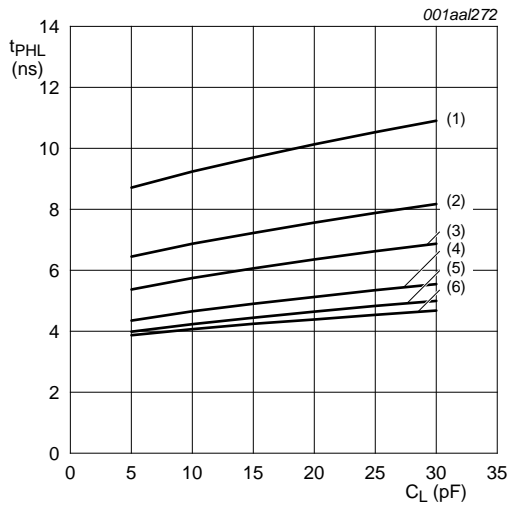


d. LOW to HIGH propagation delay (B to A)

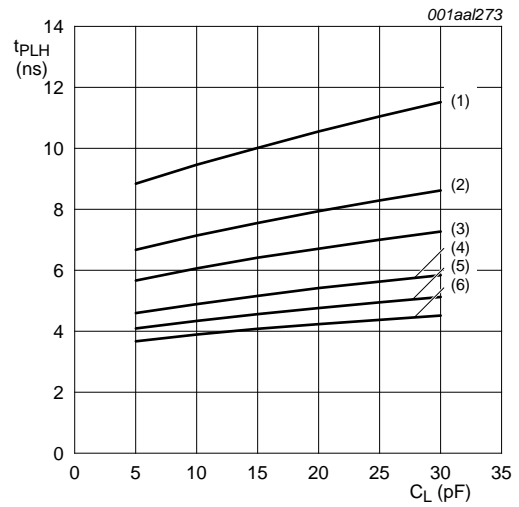
- (1)  $V_{CC(B)} = 1.2\text{ V}$ .
- (2)  $V_{CC(B)} = 1.5\text{ V}$ .
- (3)  $V_{CC(B)} = 1.8\text{ V}$ .
- (4)  $V_{CC(B)} = 2.5\text{ V}$ .
- (5)  $V_{CC(B)} = 3.3\text{ V}$ .
- (6)  $V_{CC(B)} = 5.0\text{ V}$ .

Fig 8. Typical propagation delay versus load capacitance;  $T_{amb} = 25\text{ }^\circ\text{C}$ ;  $V_{CC(A)} = 1.2\text{ V}$

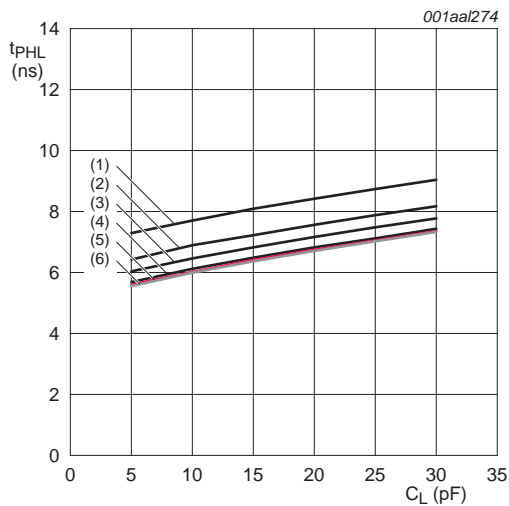




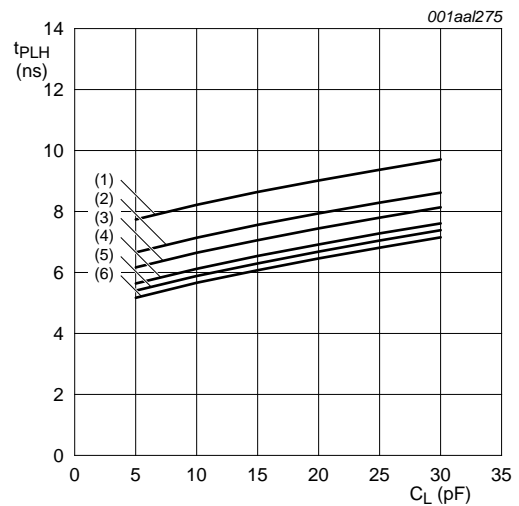
a. HIGH to LOW propagation delay (A to B)



b. LOW to HIGH propagation delay (A to B)



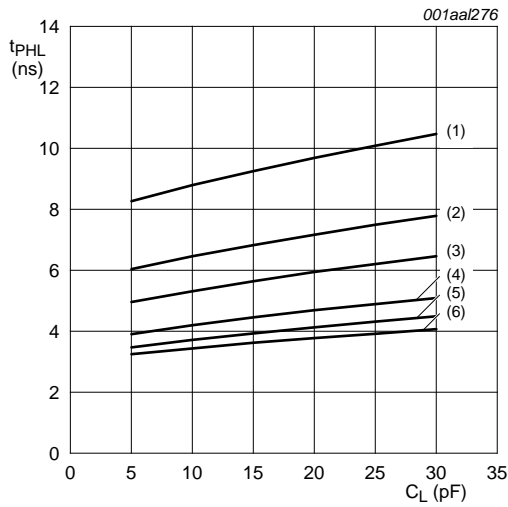
c. HIGH to LOW propagation delay (B to A)



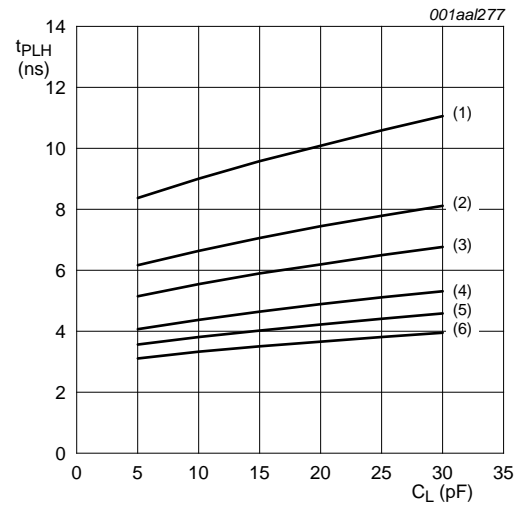
d. LOW to HIGH propagation delay (B to A)

- (1)  $V_{CC(B)} = 1.2\text{ V}$ .
- (2)  $V_{CC(B)} = 1.5\text{ V}$ .
- (3)  $V_{CC(B)} = 1.8\text{ V}$ .
- (4)  $V_{CC(B)} = 2.5\text{ V}$ .
- (5)  $V_{CC(B)} = 3.3\text{ V}$ .
- (6)  $V_{CC(B)} = 5.0\text{ V}$ .

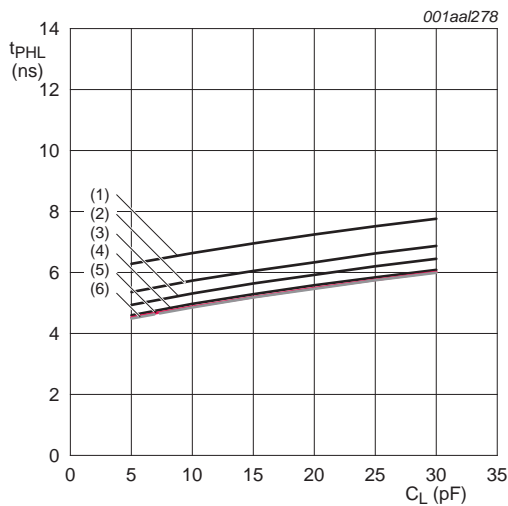
Fig 9. Typical propagation delay versus load capacitance;  $T_{amb} = 25\text{ }^\circ\text{C}$ ;  $V_{CC(A)} = 1.5\text{ V}$



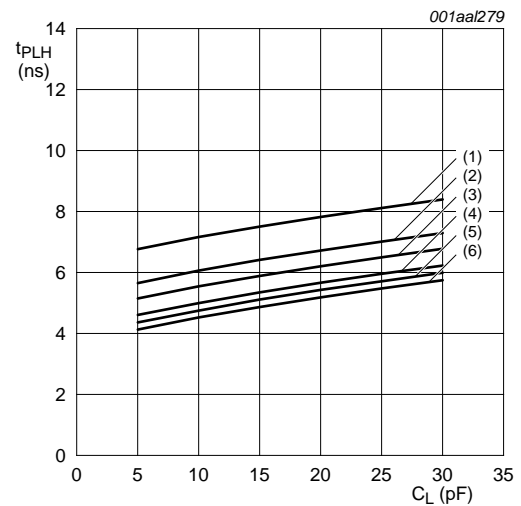
a. HIGH to LOW propagation delay (A to B)



b. LOW to HIGH propagation delay (A to B)



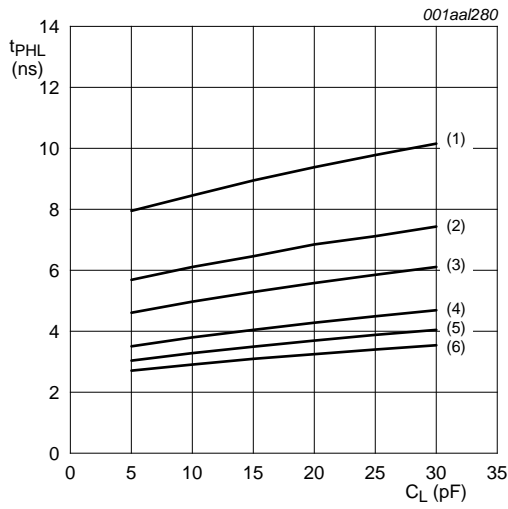
c. HIGH to LOW propagation delay (B to A)



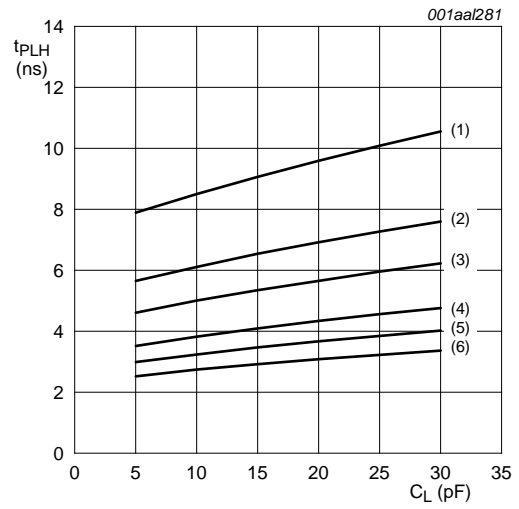
d. LOW to HIGH propagation delay (B to A)

- (1)  $V_{CC(B)} = 1.2\text{ V}$ .
- (2)  $V_{CC(B)} = 1.5\text{ V}$ .
- (3)  $V_{CC(B)} = 1.8\text{ V}$ .
- (4)  $V_{CC(B)} = 2.5\text{ V}$ .
- (5)  $V_{CC(B)} = 3.3\text{ V}$ .
- (6)  $V_{CC(B)} = 5.0\text{ V}$ .

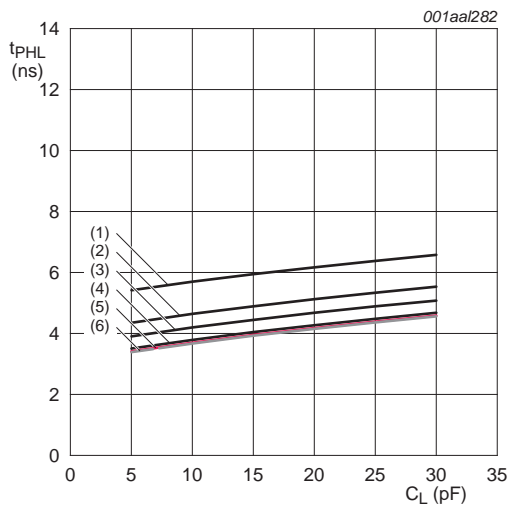
Fig 10. Typical propagation delay versus load capacitance;  $T_{amb} = 25\text{ }^\circ\text{C}$ ;  $V_{CC(A)} = 1.8\text{ V}$



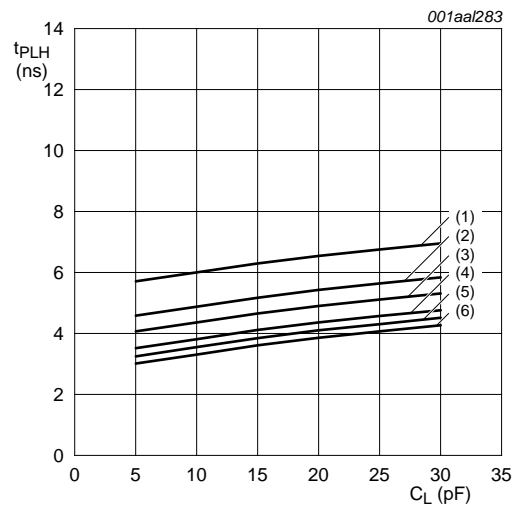
a. HIGH to LOW propagation delay (A to B)



b. LOW to HIGH propagation delay (A to B)



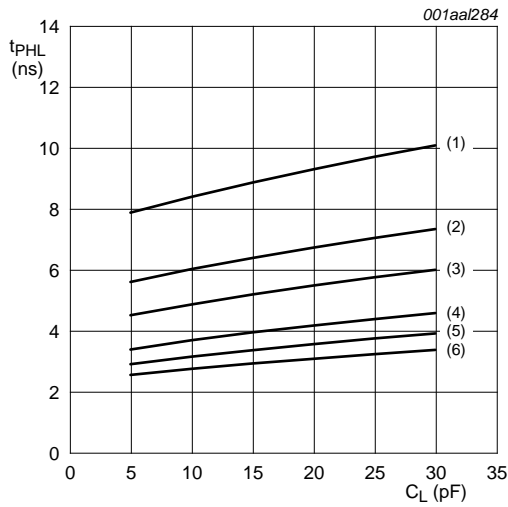
c. HIGH to LOW propagation delay (B to A)



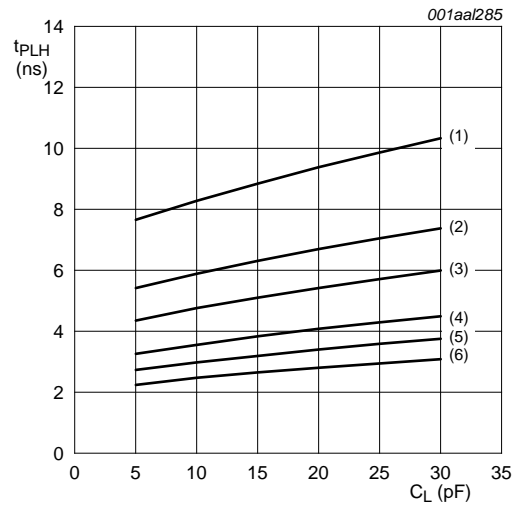
d. LOW to HIGH propagation delay (B to A)

- (1)  $V_{CC(B)} = 1.2\text{ V}$ .
- (2)  $V_{CC(B)} = 1.5\text{ V}$ .
- (3)  $V_{CC(B)} = 1.8\text{ V}$ .
- (4)  $V_{CC(B)} = 2.5\text{ V}$ .
- (5)  $V_{CC(B)} = 3.3\text{ V}$ .
- (6)  $V_{CC(B)} = 5.0\text{ V}$ .

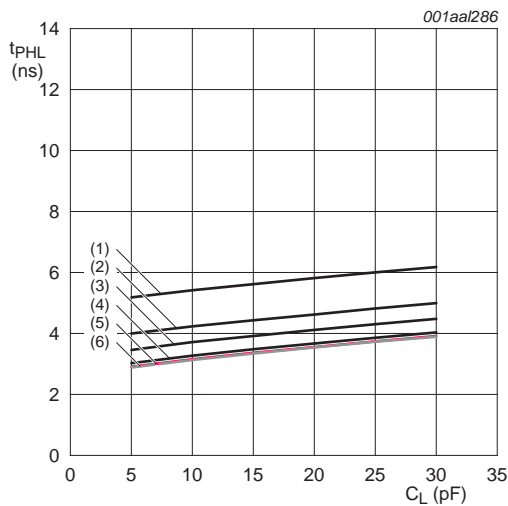
Fig 11. Typical propagation delay versus load capacitance;  $T_{amb} = 25\text{ }^\circ\text{C}$ ;  $V_{CC(A)} = 2.5\text{ V}$



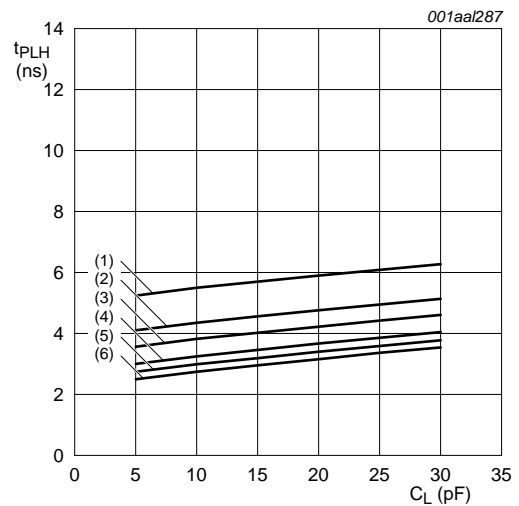
a. HIGH to LOW propagation delay (A to B)



b. LOW to HIGH propagation delay (A to B)



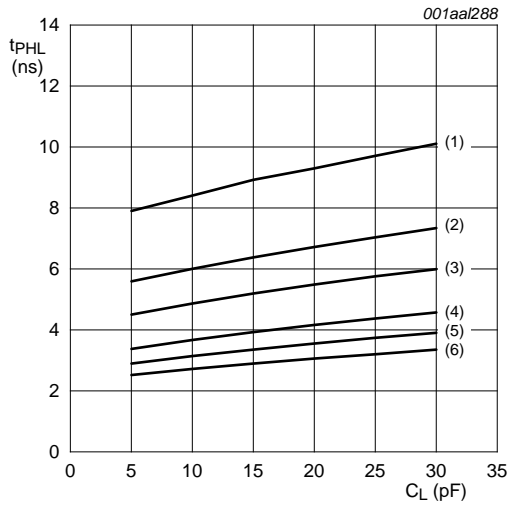
c. HIGH to LOW propagation delay (B to A)



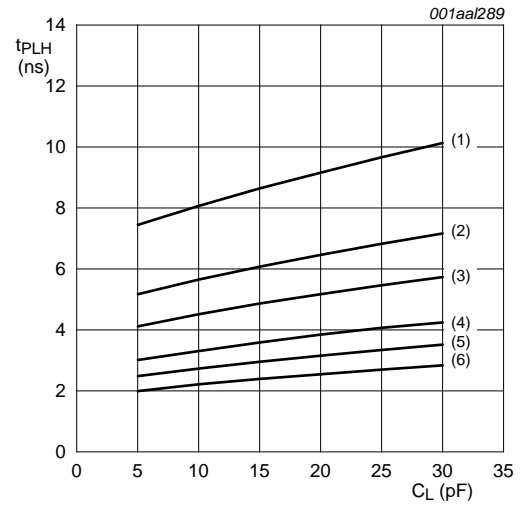
d. LOW to HIGH propagation delay (B to A)

- (1)  $V_{CC(B)} = 1.2\text{ V}$ .
- (2)  $V_{CC(B)} = 1.5\text{ V}$ .
- (3)  $V_{CC(B)} = 1.8\text{ V}$ .
- (4)  $V_{CC(B)} = 2.5\text{ V}$ .
- (5)  $V_{CC(B)} = 3.3\text{ V}$ .
- (6)  $V_{CC(B)} = 5.0\text{ V}$ .

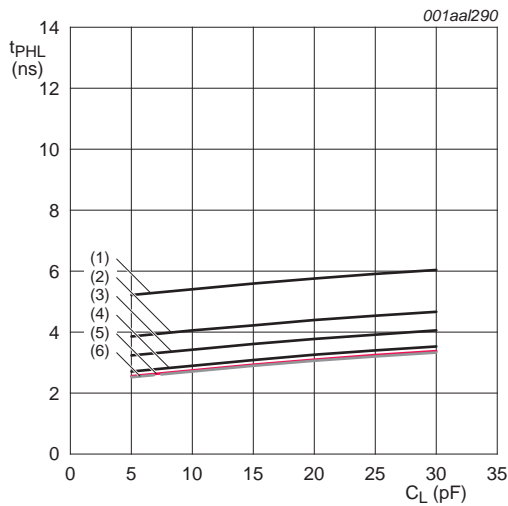
Fig 12. Typical propagation delay versus load capacitance;  $T_{amb} = 25\text{ }^\circ\text{C}$ ;  $V_{CC(A)} = 3.3\text{ V}$



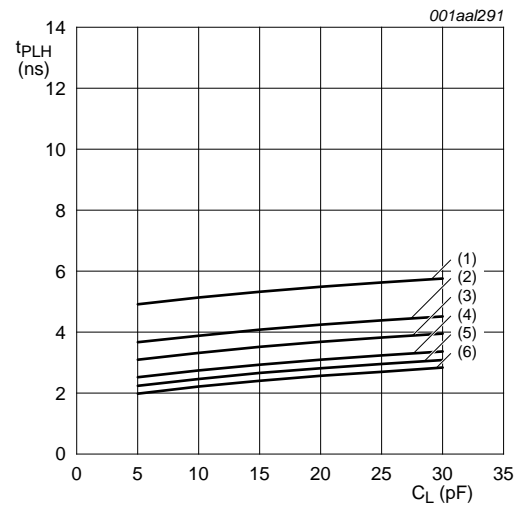
a. HIGH to LOW propagation delay (A to B)



b. LOW to HIGH propagation delay (A to B)



c. HIGH to LOW propagation delay (B to A)



d. LOW to HIGH propagation delay (B to A)

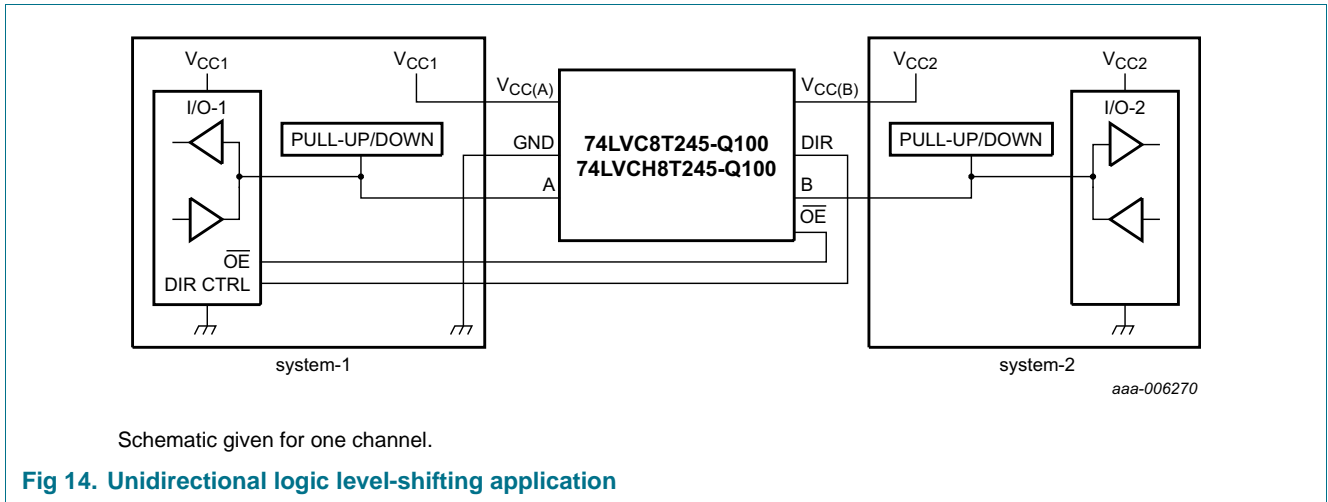
- (1)  $V_{CC(B)} = 1.2\text{ V}$ .
- (2)  $V_{CC(B)} = 1.5\text{ V}$ .
- (3)  $V_{CC(B)} = 1.8\text{ V}$ .
- (4)  $V_{CC(B)} = 2.5\text{ V}$ .
- (5)  $V_{CC(B)} = 3.3\text{ V}$ .
- (6)  $V_{CC(B)} = 5.0\text{ V}$ .

Fig 13. Typical propagation delay versus load capacitance;  $T_{amb} = 25\text{ }^\circ\text{C}$ ;  $V_{CC(A)} = 5\text{ V}$

### 13. Application information

#### 13.1 Unidirectional logic level-shifting application

The circuit given in [Figure 14](#) is an example of the 74LVC8T245-Q100; 74LVCH8T245-Q100 being used in a unidirectional logic level-shifting application.



**Table 15. Description unidirectional logic level-shifting application**

Name	Function	Description
$V_{CC(A)}$	$V_{CC1}$	supply voltage of system-1 (1.2 V to 5.5 V)
GND	GND	device GND
A	OUT	output level depends on $V_{CC1}$ voltage
B	IN	input threshold value depends on $V_{CC2}$ voltage
DIR	DIR	the GND (LOW level) determines B port to A port direction
$V_{CC(B)}$	$V_{CC2}$	supply voltage of system-2 (1.2 V to 5.5 V)
$\overline{OE}$	$\overline{OE}$	The GND (LOW level) enables the output ports

### 13.2 Bidirectional logic level-shifting application

Figure 15 shows the 74LVC8T245-Q100; 74LVCH8T245-Q100 being used in a bidirectional logic level-shifting application.

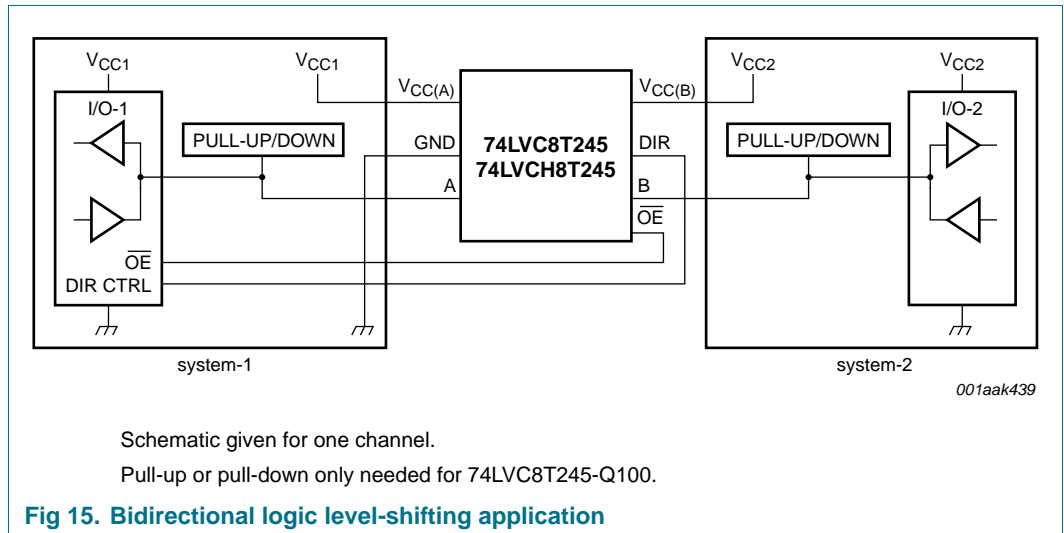


Fig 15. Bidirectional logic level-shifting application

Table 16 gives a sequence that illustrates data transmission from system-1 to system-2 and then from system-2 to system-1.

Table 16. Description bidirectional logic level-shifting application[1]

State	DIR CTRL	$\overline{OE}$	I/O-1	I/O-2	Description
1	H	L	output	input	system-1 data to system-2
2	H	H	Z	Z	system-2 is getting ready to send data to system-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on bus hold.
3	L	H	Z	Z	DIR bit is set LOW. I/O-1 and I/O-2 are still disabled. The bus-line state depends on bus hold.
4	L	L	input	output	system-2 data to system-1

[1] H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state.

### 13.3 Power-up considerations

The device is designed such that no special power-up sequence is required other than GND being applied first.

Table 17. Typical total supply current ( $I_{CC(A)} + I_{CC(B)}$ )

$V_{CC(A)}$	$V_{CC(B)}$					Unit
	0 V	1.8 V	2.5 V	3.3 V	5.0 V	
0 V	0	< 1	< 1	< 1	< 1	$\mu A$
1.8 V	< 1	< 2	< 2	< 2	2	$\mu A$
2.5 V	< 1	< 2	< 2	< 2	< 2	$\mu A$
3.3 V	< 1	< 2	< 2	< 2	< 2	$\mu A$
5.0 V	< 1	2	< 2	< 2	< 2	$\mu A$

14. Package outline

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1

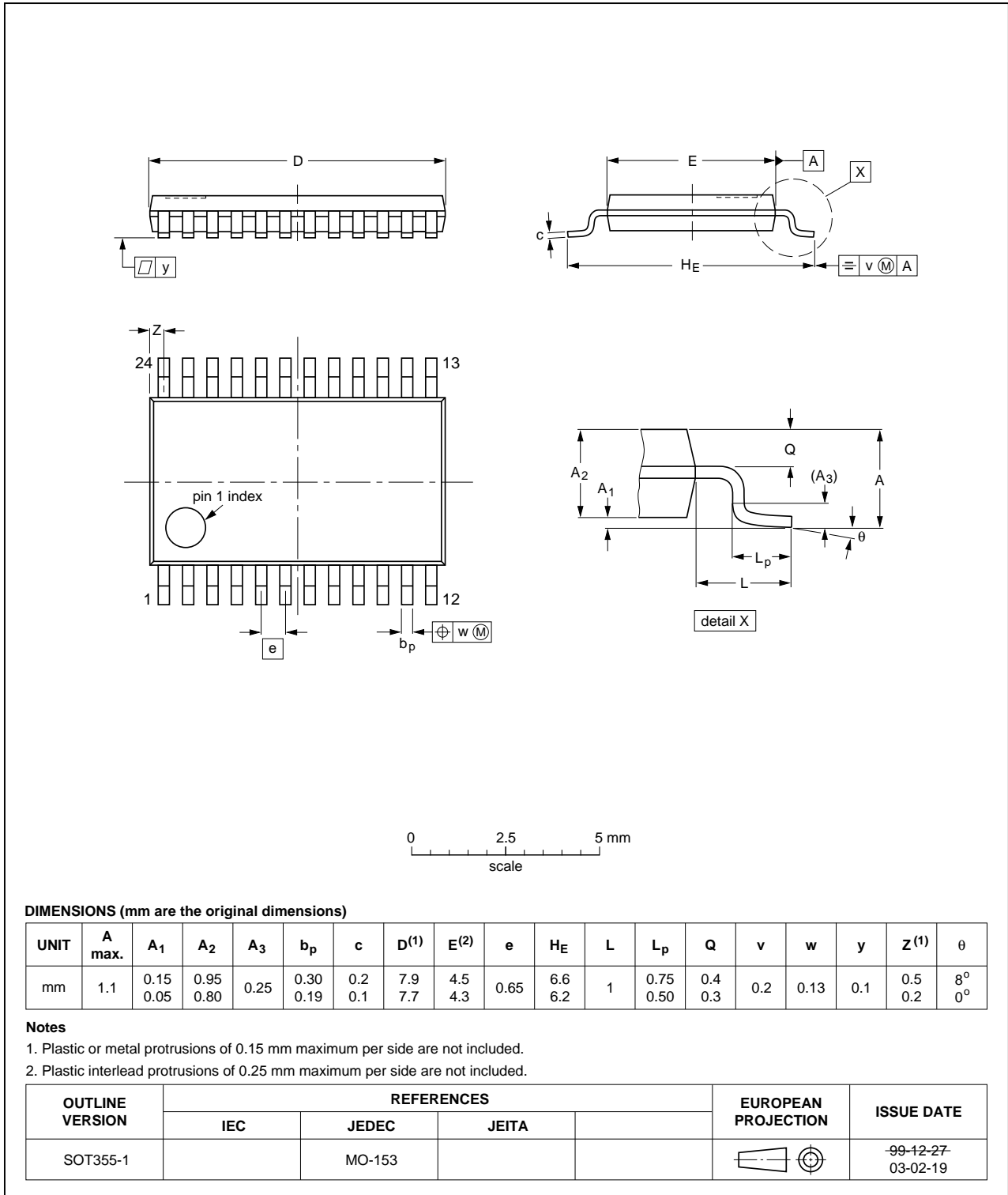


Fig 16. Package outline SOT355-1 (TSSOP24)



DHVQFN24: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3.5 x 5.5 x 0.85 mm

SOT815-1

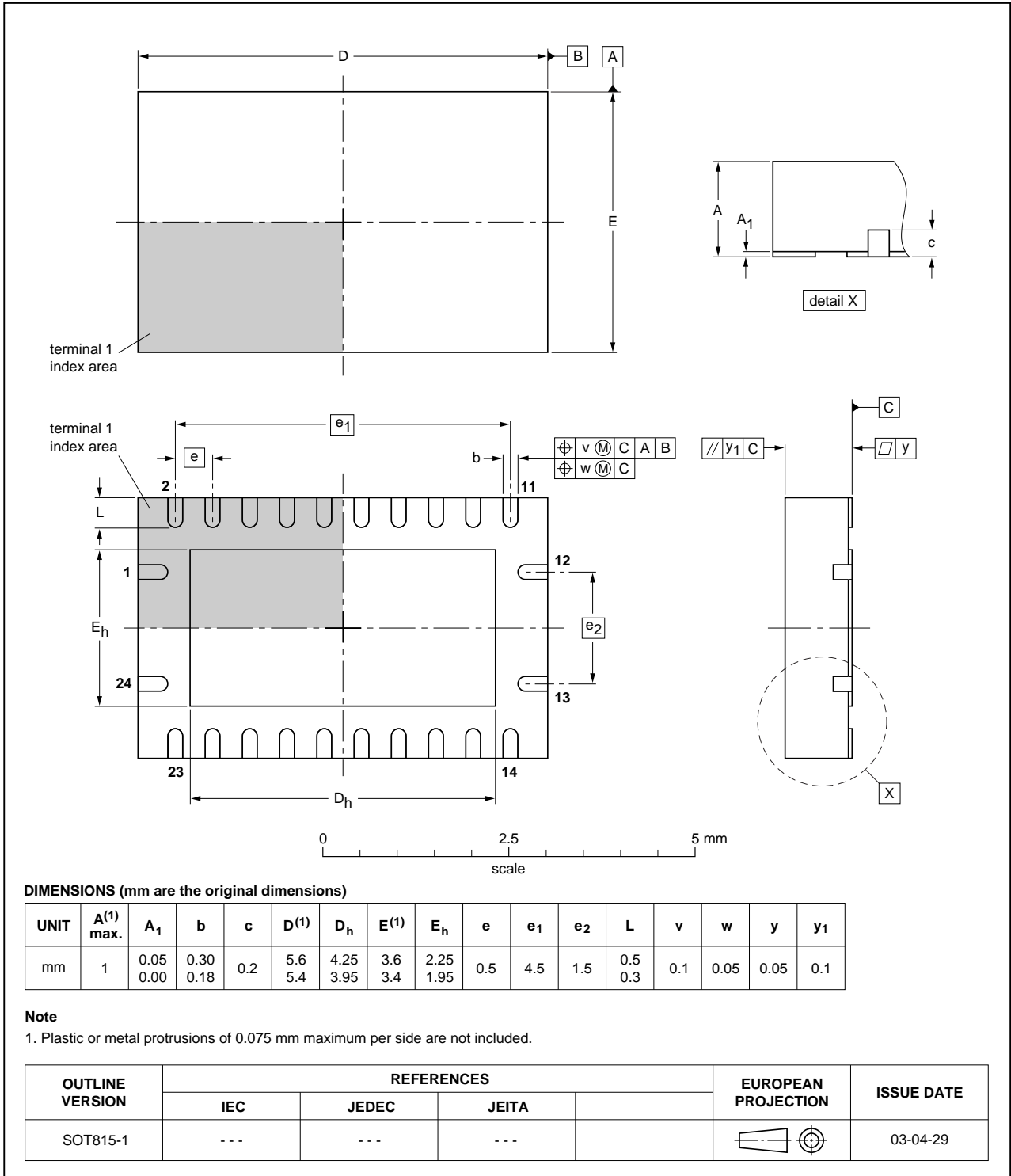


Fig 17. Package outline SOT815-1 (DHVQFN24)

## 15. Abbreviations

**Table 18. Abbreviations**

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
HBM	Human Body Model
MM	Machine Model
MIL	Military

## 16. Revision history

**Table 19. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC_LVCH8T245_Q100 v.1	20130321	Product data sheet	-	-

## 17. Legal information

### 17.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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